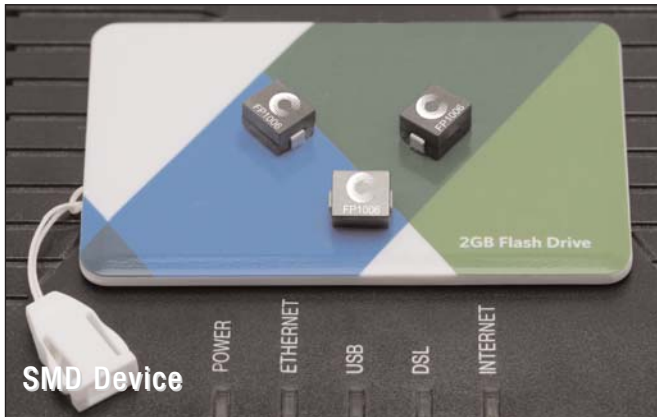


High Current, High Frequency, Low-Profile Power Inductors

FLAT-PAC™ FP1006 Series



Description

- Halogen free
- 125°C maximum total temperature operation
- 10.2 x 8.0 x 6.0mm surface mount package
- Ferrite core material
- High current carrying capacity, Low core losses
- Controlled DCR tolerance for sensing circuits
- Inductance range from 85nH to 220nH
- Current range from 38 to 100 amps
- Frequency range up to 2MHz
- RoHS compliant

Applications

- Multi-phase regulators
- Voltage Regulator Module (VRM)
- Point-of-load modules
- Desktop and server VRMs and EVRDs
- Data networking and storage systems
- Notebook regulators
- Graphics cards and battery power systems
- DCR sensing

Environmental Data

- Storage temperature range: -40°C to +125°C
- Operating temperature range: -40°C to +125°C (Range is application specific)
- Solder reflow temperature: J-STD-020D compliant

Packaging

- Supplied in tape and reel packaging, 850 parts per reel, 13" diameter reel

Product Specifications

| Part Number ⁷ | OCL ¹ ± 10% (nH) | FLL ² Min. (nH) | I _{rms} ³ (Amps) | I _{sat} ¹⁴ @ 25°C (Amps) | I _{sat} ²⁵ @ 125°C (Amps) | DCR (mΩ) @ 20°C | K-factor ⁶ |
|--------------------------|-----------------------------|----------------------------|--------------------------------------|--|---|-----------------|-----------------------|
| R1 Version | | | | | | | |
| FP1006R1-R08-R | 85 | 61 | 53 | 100 | 70 | 0.27 ± 12% | 454 |
| FP1006R1-R10-R | 100 | 72 | | 85 | 64 | | 454 |
| FP1006R1-R12-R | 120 | 86 | | 71 | 53 | | 454 |
| FP1006R1-R16-R | 160 | 115 | | 55 | 40 | | 454 |
| FP1006R1-R22-R | 220 | 158 | | 38 | 28 | | 454 |
| R2 Version | | | | | | | |
| FP1006R2-R08-R | 85 | 61 | 45 | 100 | 70 | 0.36 ± 8.6% | 454 |
| FP1006R2-R10-R | 100 | 72 | | 85 | 64 | | 454 |
| FP1006R2-R12-R | 120 | 86 | | 71 | 53 | | 454 |
| FP1006R2-R16-R | 160 | 115 | | 55 | 40 | | 454 |
| FP1006R2-R22-R | 220 | 158 | | 38 | 28 | | 454 |

1 Open Circuit Inductance (OCL) Test Parameters: 100kHz, 0.10V_{rms}, 0.0Adc

2 Full Load Inductance (FLL) Test Parameters: 100kHz, 0.1V_{rms}, I_{sat}¹

3 I_{rms}: DC current for an approximate temperature rise of 40°C without core loss. Derating is necessary for AC currents. PCB pad layout, trace thickness and width, air-flow and proximity of other heat generating components will affect the temperature rise. It is recommended the part temperature not exceed 125°C under worst case operating conditions verified in the end application.

4 I_{sat}¹: Peak current for approximately 20% rolloff at +25°C.

5 I_{sat}²: Peak current for approximately 20% rolloff at +125°C.

6 K-factor: Used to determine B_{p-p} for core loss (see graph). B_{p-p} = K · L · ΔI · 10⁻³, B_{p-p}: (Gauss), K: (K-factor from table), L: (inductance in nH), ΔI (peak-to-peak ripple current in amps).

7 Part Number Definition: FP1006Rx-Rxx-R

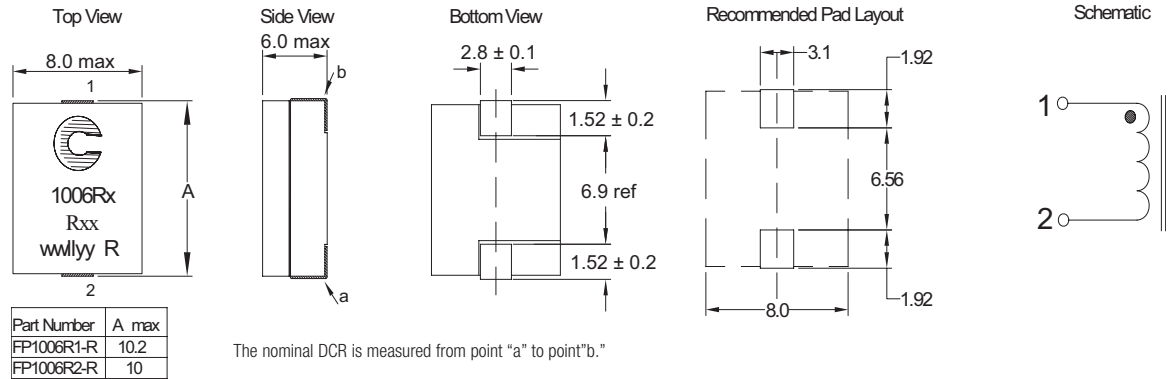
• FP1006 = Product code and size

• Rx is the DCR indicator

• Rxx= Inductance value in μH, R = decimal point

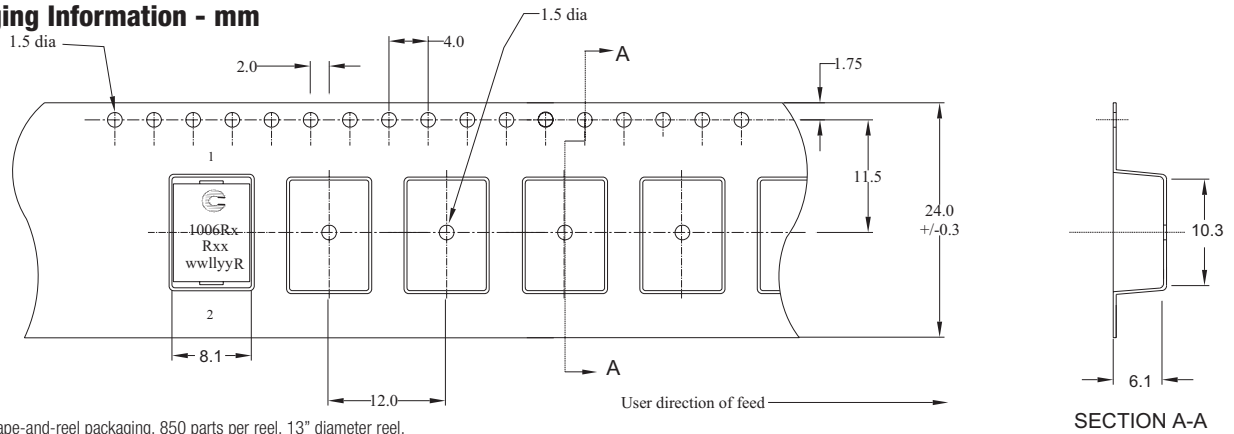
• "-R" suffix = RoHS compliant

Dimensions - mm



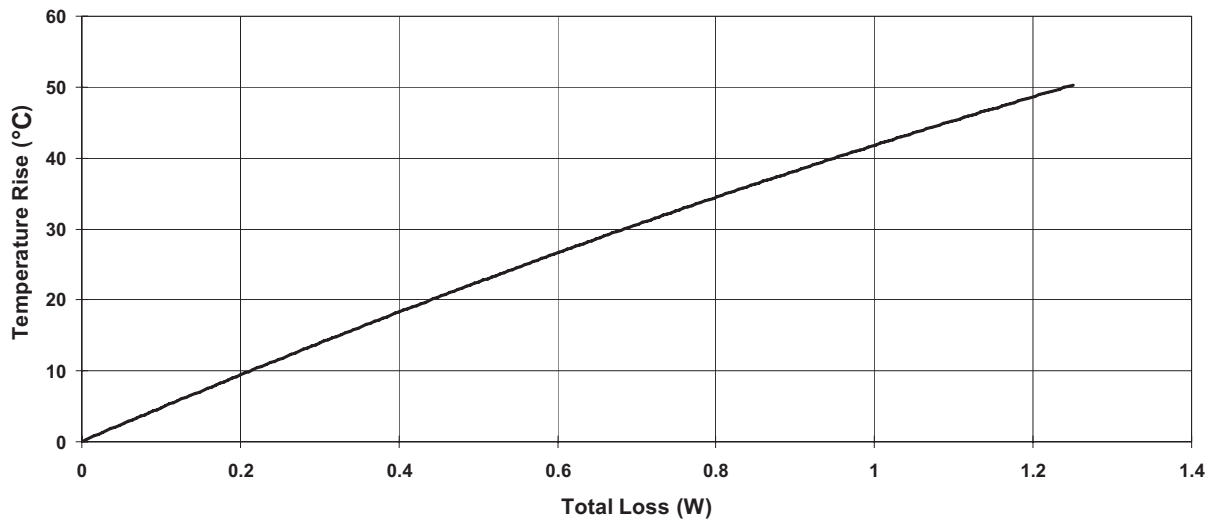
Part Marking: Coiltronics Logo 1006Rx (Rx = DCR Indicator) Rxx = Inductance value in μH . (R = Decimal point) wwlyyy = Date code R = Revision level

Packaging Information - mm

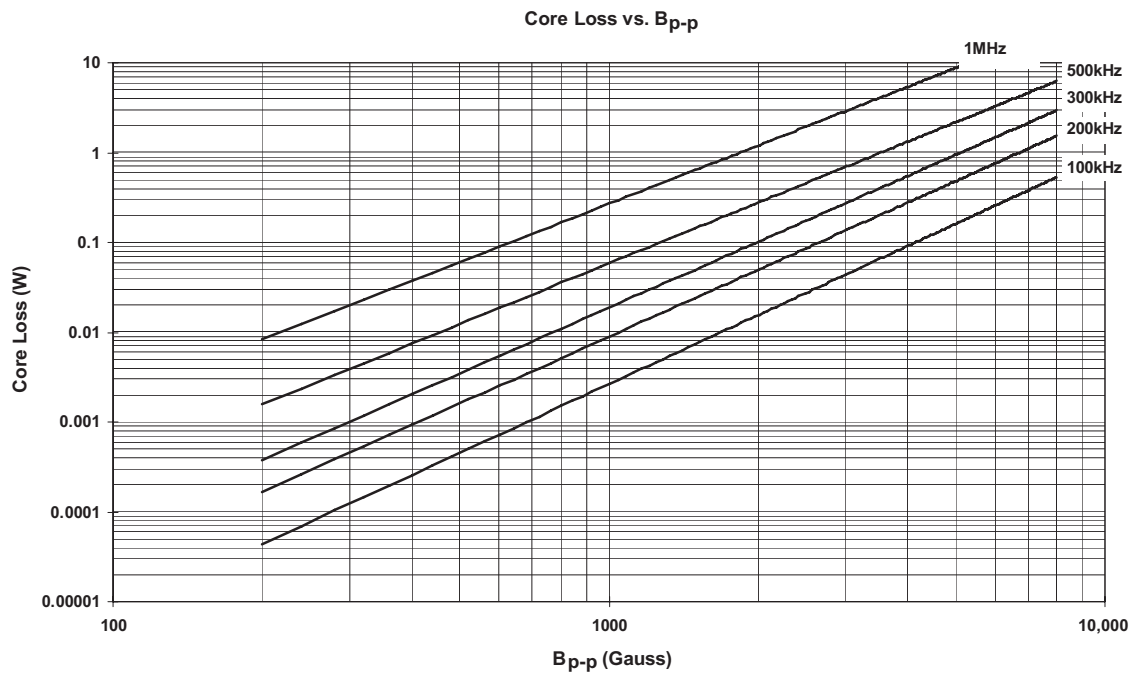


Supplied in tape-and-reel packaging, 850 parts per reel, 13" diameter reel.

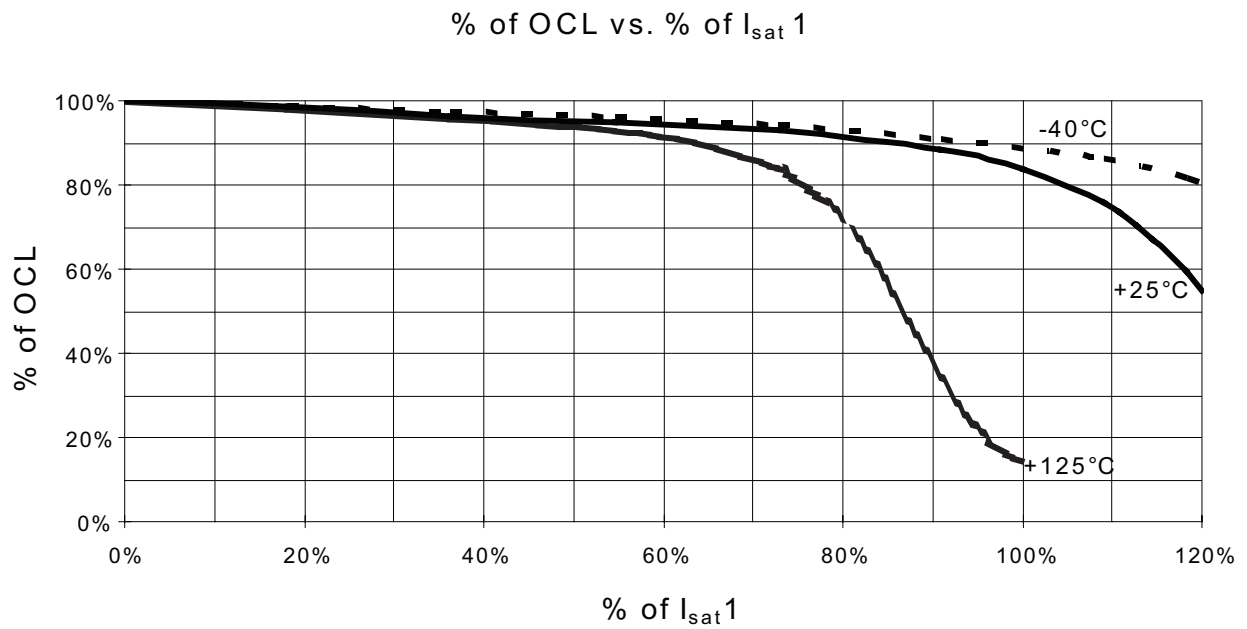
Temperature Rise vs. Total Loss



Core Loss



Inductance Characteristics



Solder Reflow Profile

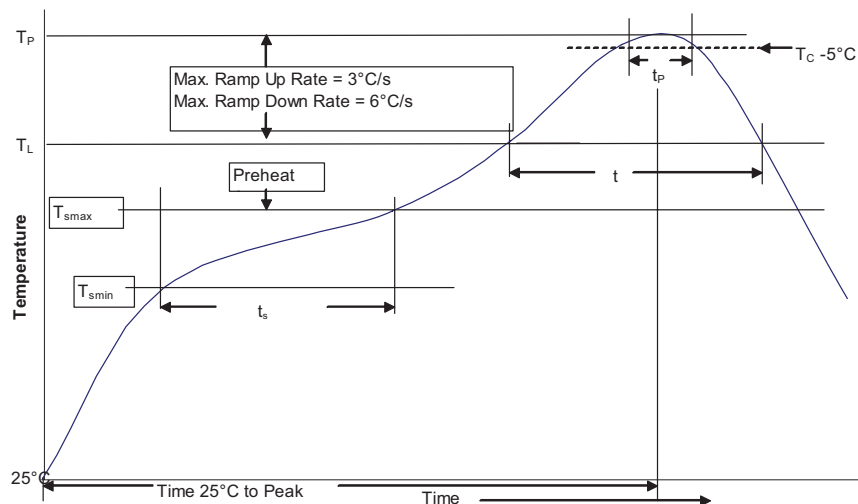


Table 1 - Standard SnPb Solder (T_C)

| Package Thickness | Volume mm^3 <350 | Volume mm^3 ≥ 350 |
|-------------------|--------------------|--------------------------|
| <2.5mm | 235°C | 220°C |
| $\geq 2.5mm$ | 220°C | 220°C |

Table 2 - Lead (Pb) Free Solder (T_C)

| Package Thickness | Volume mm^3 <350 | Volume mm^3 350 - 2000 | Volume mm^3 >2000 |
|-------------------|--------------------|--------------------------|---------------------|
| <1.6mm | 260°C | 260°C | 260°C |
| 1.6 - 2.5mm | 260°C | 250°C | 245°C |
| >2.5mm | 250°C | 245°C | 245°C |

Reference JDEC J-STD-020D

| Profile Feature | Standard SnPb Solder | Lead (Pb) Free Solder |
|--|----------------------|-----------------------|
| Preheat and Soak | | |
| • Temperature min. (T_{smin}) | 100°C | 150°C |
| • Temperature max. (T_{smax}) | 150°C | 200°C |
| • Time (T_{smin} to T_{smax}) (t_s) | 60-120 Seconds | 60-120 Seconds |
| Average ramp up rate T_{smax} to T_P | 3°C/ Second Max. | 3°C/ Second Max. |
| Liquidous temperature (T_L) | 183°C | 217°C |
| Time at liquidous (t_L) | 60-150 Seconds | 60-150 Seconds |
| Peak package body temperature (T_P)* | Table 1 | Table 2 |
| Time (t_p)** within 5 °C of the specified classification temperature (T_C) | 20 Seconds** | 30 Seconds** |
| Average ramp-down rate (T_P to T_{smax}) | 6°C/ Second Max. | 6°C/ Second Max. |
| Time 25°C to Peak Temperature | 6 Minutes Max. | 8 Minutes Max. |

* Tolerance for peak profile temperature (T_P) is defined as a supplier minimum and a user maximum.

** Tolerance for time at peak profile temperature (t_p) is defined as a supplier minimum and a user maximum.

North America

Cooper Electronic Technologies
1225 Broken Sound Parkway NW
Suite F
Boca Raton, FL 33487-3533
Tel: 1-561-998-4100
Fax: 1-561-241-6640
Toll Free: 1-888-414-2645

Cooper Bussmann
P.O. Box 14460
St. Louis, MO 63178-4460
Tel: 1-636-394-2877
Fax: 1-636-527-1607

Europe

Cooper Electronic Technologies
Cooper (UK) Limited
Burton-on-the-Wolds
Leicestershire • LE12 5TH UK
Tel: +44 (0) 1509 882 737
Fax: +44 (0) 1509 882 786

Cooper Electronic Technologies
Avda. Santa Eulalia, 290
08223
Terrassa, (Barcelona), Spain
Tel: +34 937 362 812
+34 937 362 813
Fax: +34 937 362 719

Asia Pacific

Cooper Electronic Technologies
1 Jalan Kilang Timor
#06-01 Pacific Tech Centre
Singapore 159303
Tel: +65 278 6151
Fax: +65 270 4160

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